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SEMICONDUCTOR



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MURSXXXT3G-MS

Product specification



SURFACE MOUNT ULTRAFAST POWER RECTIFIERS DIODES**VOLTAGE RANGE: 50 - 600V****CURRENT: 1.0A****Features**

- Glass Passivated Die Construction
- Ideally Suited for Automatic Assembly
- Low Forward Voltage Drop, High Efficiency
- Low Power Loss
- Super-Fast Recovery Time
- Plastic Case Material has UL Flammability Classification Rating 94V-O

Mechanical Data

- Case: SMA/DO-214AA, Molded Plastic
- Terminals: Solder Plated, Solderable
- per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Weight: 0.093 grams (approx.)

Reference News

PACKAGE OUTLINE	Marking
	
SMB(DO-214AA)	*** Representative VRRM

Maximum Ratings and Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise specified Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic		Symbol	MURS105 T3G-MS	MURS11 0T3G-MS	MURS115 T3G-MS	MURS120 T3G-MS	MURS130 T3G-MS	MURS140 T3G-MS	MURS160 T3G-MS	Unit
Peak Repetitive Reverse Voltage		V_{RRM}								V
Working Peak Reverse Voltage		V_{RWM}	50	100	150	200	300	400	600	
DC Blocking Voltage		V_R								
RMS Reverse Voltage		$V_{R(RMS)}$	35	70	105	140	210	280	420	V
Average Rectified Output Current	$T_L = 150^\circ\text{C}$	I_o	1.0						A	
	$T_L = 125^\circ\text{C}$		2.0							
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)		I_{FSM}	40				35			A
Forward Voltage @ $I_F = 1.0\text{A}$		V_{FM}	0.875				1.25			V
Peak Reverse Current At Rated DC Blocking Voltage	@ $T_A = 25^\circ\text{C}$	I_{RM}	10.0						μA	
	@ $T_A = 100^\circ\text{C}$		150							
Reverse Recovery Time (Note 1)		t_{rr}	35						nS	
Typical Junction Capacitance (Note 2)		C_j	25						pF	
Typical Thermal Resistance (Note 3)		$R_{\theta JL}$	13						$^\circ\text{C/W}$	
Operating and Storage Temperature Range		T_j, T_{STG}	-65 to +150						$^\circ\text{C}$	

Note: 1.Reverse recovery condition $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$
 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 3.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

RATINGS AND CHARACTERISTIC CURVES MURSXXXT3G-MS

Fig. 1 — Forward Current Derating Curve

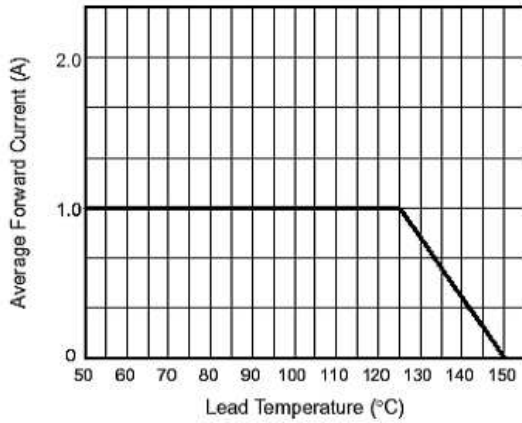


Fig. 2 — Maximum Non-Repetitive Peak Forward Surge Current

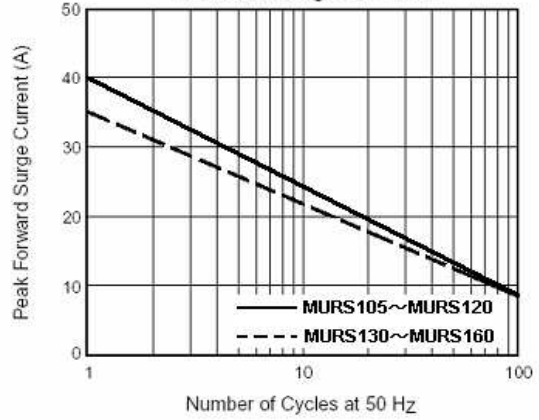


Fig. 3 — Typical Instantaneous Forward Characteristics

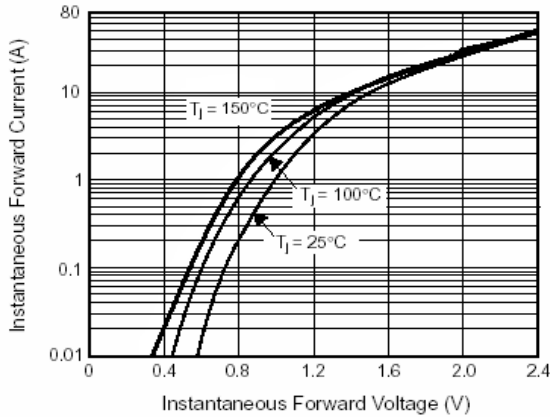


Fig. 4 — Typical Reverse Leakage Characteristics

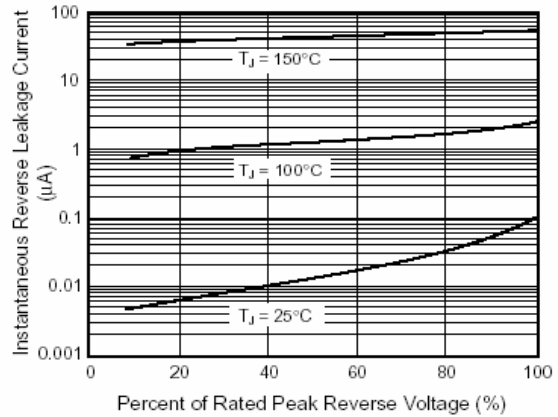
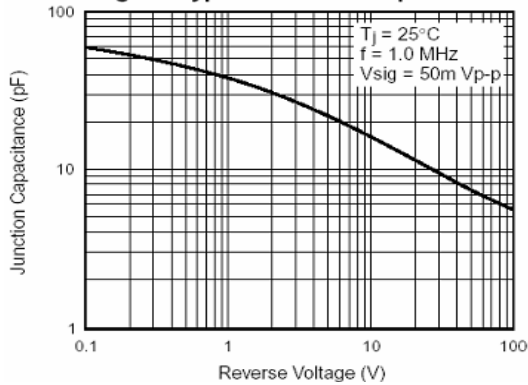
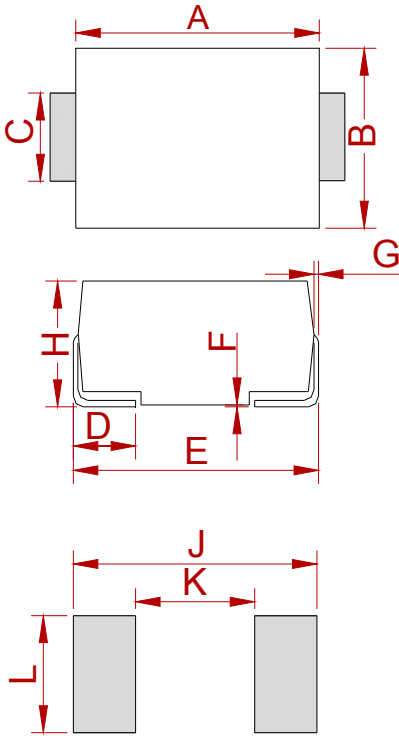


Fig. 5 — Typical Junction Capacitance



PACKAGE MECHANICAL DATA



DO-214AA (SMB)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.75	0.167	0.187
B	3.30	3.94	0.130	0.155
C	1.85	2.21	0.073	0.087
D	0.76	1.52	0.030	0.060
E	5.08	5.59	0.200	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.11	2.44	0.083	0.096
J	6.80		0.270	
K		2.60		0.100
L	2.40		0.090	

REEL SPECIFICATION

P/N	PKG	QTY
MURSXXXT3G-MS	DO-214AA(SMB)	2500

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